

GRN3 THRU GRN7

SURFACE MOUNT GLASS PASSIVATED JUNCTION FAST SWITCHING RECTIFIER Reverse Voltage - 50 to 600 Volts Forward Current - 1.0 Ampere

SMA

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Ideal for surface mount automotive applications
- High temperature metallurgically bonded construction
- Glass passivated cavity-free junction
- Capable of meeting environmental standards of MIL-S-19500
- Built-in strain relief
- Easy pick and place
- Fast switching for high efficiency
- High temperature soldering guaranteed: 450°C/5 seconds at terminals
- Complete device submersible temperature of 265℃ for 10 seconds in solder bath

Mechanical Data

- Case: SMA molded plastic over glass body
- Terminals: Solder plated, solderable per MIL-STD-750, method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.004 ounce, 0.118 gram

Maximum Ratings and Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.

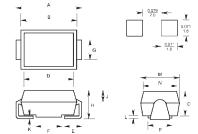
	Symbols	GRN3	GRN4	GRN5	GRN6	GRN7	Units
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	Volts
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	Volts
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	Volts
Maximum average forward rectified current at $\rm T_L=120{}^\circ\!C$	I _(AV)	1.0					Amp
Peak forward surge current 8.3mS single half sine-wave superimposed on rated load (MIL-STD-750D 4066 method)	I _{FSM}	30.0					Amps
Maximum instantaneous forward voltage at 1.0A	V _F	1.30					Volts
Maximum full load reverse current, full cycle average, $T_{\rm A}{=}55{\rm °C}$	I _{R(AV)}	50.0				μA	
$\begin{array}{llllllllllllllllllllllllllllllllllll$	I _R	5.0 100.0				μA	
Maximum reverse recovery time (Note 1)	T _{rr}	1:	50 250		500	nS	
Typical junction capacitance (Note 2)	C	8.5					ρF
Typical thermal resistance (Note 3)	R _{☉JA} R _{☉JL}	85.0 28.0					°C/W
Operating junction and storage temperature range	T _J , T _{stg}	-65 to +175			°C		

Notes:

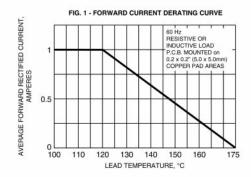
(1) Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_r=0.25A

(2) Measured at 1.0MHz and applied reverse voltage of 4.0 volts

(3) Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2X0.2" (5.0X5.0mm) copper pad areas



D IM E N S IO N S								
DIM	inches		m	Note				
	M in .	Max.	M in .	Max.	Note			
A	0.216	0.226	5.48	5.74				
В	0.176	0.182	4.48	4.63				
с	0.094	0.100	2.40	2.55				
D	0.170	0.176	4.33	4.48				
E	0.039	0.055	1.00	1.40				
F	0.080	0.081	2.03	2.07				
G	0.068	0.083	1.72	2.10				
н	0.112	0.118	2.85	3.00				
J	0.057		1.44					
к		0.018	-	0.45				
L	0.016		0.40					
м	0.109	0.115	2.77	2.93				
N	0.105	0.107	2.67	2.73				
Р	0.078	0.081	2.00	2.05				



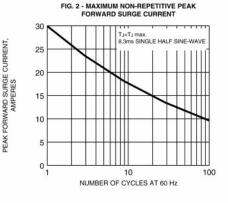


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

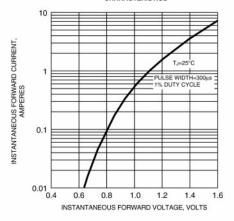
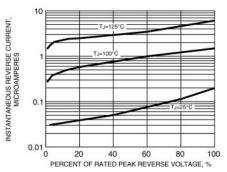


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

FIG. 4 - TYPICAL REVERSE CHARACTERISTICS



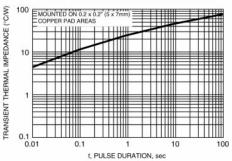


FIG. 6 - TYPICAL TRANSIENT THERMAL IMPEDANCE